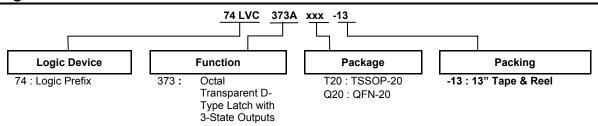


Ordering Information



Part Number	Package	Package	Package	13" Tape	and Reel
Part Number	Code	(Note 4 & 5)	Size	Quantity	Part Number Suffix
74LVC373AT20-13	T20	TSSOP-20	6.4mm X 6.5mm X 1.2mm 0.65 mm lead pitch	2500/Tape & Reel	-13
74LVC373AQ20-13	Q20	V-QFN4525-20	2.5mm X 4.5mm X 0.95mm 0.50 mm lead pitch	2500/Tape & Reel	-13

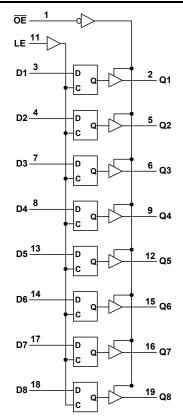
Notes:

- 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 5. V-QFN4525-20 is a JEDEC recognized naming convention that specifies the package thickness category as V and the number 4525 describes the package as 4.5mm X 2.5mm.

Pin Descriptions

= : • • · · · · · · · · · · · · ·						
Pin Number	Pin Name	Description				
1	ŌĒ	Output Enable				
2	Q1	Latch Output				
3	D1	Data Input				
4	D2	Data Input				
5	Q2	Latch Output				
6	Q3	Latch Output				
7	D3	Data Input				
8	D4	Data Input				
9	Q4	Latch Output				
10	GND	Ground				
11	LE	Latch Enable				
12	Q5	Latch Output				
13	D5	Data Input				
14	D6	Data Input				
15	Q6	Latch Output				
16	Q7	Latch Output				
17	D7	Data Input				
18	D8	Data Input				
19	Q8	Latch Output				
20	Vcc	Supply Voltage				

Logic Diagram



Function Table

(Each Latch)						
	INPUTS	OUTPUT				
ŌE	LE	D	Q			
L	Н	Н	Н			
L	Н	L	L			
L	L	Х	Q_0			
Н	Х	Х	Z			



Absolute Maximum Ratings (Notes 6 & 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to +7.0	V
VI	Input Voltage Range	-0.5 to +7.0	V
I _{IK}	Input Clamp Current V _I < 0V	-20	mA
lok	Output Clamp Current V _O < 0V	-50	mA
Io	Continuous Output Current -0.5V < V _O V _{CC} +0.5V	±50	mA
Icc	Continuous Current Through V _{CC}	100	mA
I _{GND}	Continuous Current Through GND	-100	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
P _{TOT}	Total Power Dissipation	500	mW

Notes:

- 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
- 7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 8)

Symbol	Parameter	Conditions	Min	Max	Unit
	Cumply Voltage	Operating	1.65	3.6	V
V _{CC}	Supply Voltage	Data Retention Only	1.5	_	V
VI	Input Voltage	_	0	5.5	V
Vo	Output Voltage	_	0	V _{CC}	V
	I _{OH} High-Level Output Current	V _{CC} = 1.65V	_	-4	
		V _{CC} = 2.3V	_	-8	A
ЮН		V _{CC} = 2.7V	_	-12	mA mA
		V _{CC} = 3.0V	_	-24	
		V _{CC} = 1.65V	_	4	
	Law Lawal Outrot Comment	V _{CC} = 2.3V	_	8	^
l _{OL}	Low-Level Output Current	V _{CC} = 2.7V	_	12	mA mA
		V _{CC} = 3.0V	_	24	
Δt/ΔV	Input Transition Rise or Fall Rate		_	10	ns/V
T _A	Operating Free-Air Temperature		-40	+125	°C

Note:

8. Unused inputs should be held at V_{CC} or ground.



Electrical Characteristics

Cumbal	Parameter	Test Conditions	V	T _A = -40°0	C to +85°C	T _A = +85°C	to +125°C	Unit
Symbol	r arameter rest conditions		V _{CC}	Min	Max	Min	Max	Unit
			1.65V to 1.95V	V _{CC} X 0.65	_	V _{CC} X 0.65	_	
V_{IH}	High-Level Input Voltage		2.3V to 2.7V	1.7	_	1.7	_	V
	Voltage		3.0V to 3.6V	2	_	2	_	
	Lave Lavel Invest		1.65V to 1.95V	_	V _{CC} X 0.35	_	V _{CC} X 0.35	
V_{IL}	Low-Level Input Voltage		2.3V to 2.7V	_	0.7	_	0.7	V
	Voltago		3.0V to 3.6V	_	0.8	_	0.8	
		I _{OH} = -50μA	1.65V to 3.6V	V _{CC} -0.2	_	V _{CC} -0.3	_	
		I _{OH} = -4mA	1.65V	1.2	_	1.05	_	
\/	High-Level Output	I _{OH} = -8mA	2.3V	1.7	_	1.65	_	
V_{OH}	OH Voltage	1 40 4	2.7V	2.2	_	2.05	_	V
		$I_{OH} = -12mA$	3.0V	2.4	_	2.48	_	V
		I _{OH} = -24mA	3.0V	2.3	_	2.0	_	
		I _{OL} = 100μA	1.65V to 3.6V	_	0.2	_	0.3	
	Low-Level Output Voltage	I _{OL} = 4mA	1.65V	_	0.45	_	0.65	
V_{OL}		I _{OL} = 8mA	2.3V	_	0.60	_	0.80	V
		I _{OL} = 12mA	2.7V	_	0.40	_	0.60	
		I _{OL} = 24mA	3.0V	_	0.55	_	0.80	
I _{OFF}	Power Down Leakage Current	V_1 or $V_0 = 0$ or 5.5V	0V	_	±10	_	20	μA
II	Input Current Control Pins	V _I = GND or 5.5V	0 to 3.6V	_	±5	_	±20	μA
l _{OZ}	Z-state Current Including Input Current I/O Pins	V _I = GND or 5.5V V _O = 0 to 5.5V	3.6V	_	±5	_	±20	μA
Icc	Supply Current	$V_I = GND \text{ or } V_{CC}, I_O = 0$	3.6V	_	10	_	40	μA
Δlcc	Additional Supply Current	One input at Vcc-0.6V lo = 0A	2.7V to 3.6V	_	500	_	5000	μA
0	Innut Canacitanas	Control Pins $V_1 = GND$ or	0V to 3.6V	4.0 ty	ypical	4.0 ty	/pical	nE
Ci	Input Capacitance	I/O Pins V _{CC}	0 0 10 3.60	5.5 t	ypical	5.5 ty	/pical	pF



Switching Characteristics

Comple ed	Damamatan	Test	.,		T _A = +25°C	:	-40°C to	+85°C	+85°C to	+125°C	Unit	
Symbol	Parameter	Conditions	V _{cc}	Min	Тур.	Max	Min	Max	Min	Max	Unit	
			1.8V ± 0.15V	5.0	2.5		5.0		5.5			
	Pulse Width	F: 1	2.5V ± 0.3V	4.0	2.0		4.0		4.5			
t _W	LE	Figure 1	2.7V	3.0	1.7		3.0		3.5		ns	
			$3.3V \pm 0.3$	3.0	1.5		3.0		3.5			
			1.8V ± 0.15V	4.0	2.0		4.0		4.5			
	Set-up Time D _N to	E. 4	2.5V ± 0.3V	3.0	1.5		3.0		3.5			
t _{su}	LE	Figure 1	2.7V	2.0	1.0		2.0		2.5		ns	
			3.3V ± 0.3	2.0	1.0		2.0		2.5			
			1.8V ± 0.15V	3.0	1.5		3.0		3.5			
	Hold Time		2.5V ± 0.3V	2.0	1.0		2.0		2.5			
t _H	D _N to LE	Figure 1	2.7V	1.5	1.0		1.5		2.0		ns	
			3.3V ± 0.3	1.5	1.0		1.5		2.0			
			1.8V ± 0.15V	1	6	12.2	1	12.7	1	16.9		
	$t_{PD} \qquad \begin{array}{c} \text{Propagation Delay} \\ D_{N} \text{ to } Q_{N} \end{array}$			2.5V ± 0.3V	1	3.9	7.8	1	8.3	1	8.7	
t_{PD}		Figure 1	2.7V	1	4.2	7.8	1	7.3	1	9.5	ns	
				3.3V ± 0.3	1.5	3.8	6.8	1.5	6.3	1.5	8.0	
			1.8V ± 0.15V	1	7	14.8	1	15.3	1	22.5		
	Propagation Delay		2.5V ± 0.3V	1	4.5	10	1	10.5	1	12.4		
t _{PD}	LE to Q _N	Figure 1	2.7V	1	5.4	8.2	1	9.5	1	12.0	ns	
			3.3V ± 0.3	1.5	4.4	7.2	1.5	8.5	1.5	11.0		
			1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2		
	Enable Time		2.5V ± 0.3V	1	4	9	1	9.5	1	8.2		
t _{EN}	\overline{OE} to Q_N	Figure 1	2.7V	1	4.4	8.3	1	8.5	1	10.0	ns	
	O L to QN		3.3V ± 0.3	1.7	4.1	7.3	1.7	7.5	1.7	9.0		
			1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2		
	Disable Time		2.5V ± 0.3V	1	4	9	1	9.5	1	8.2		
t _{DIS}	\overline{OE} to Q_N	Figure 1	2.7V	1	4.4	8.3	1	8.5	1	10.0	ns	
			3.3V ± 0.3	1.7	4.1	7.3	1.7	7.5	1.7	9.0		
		1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2			
	Disable Time	able Time	2.5V ± 0.3V	1	4	9	1	9.5	1	8.2		
t _{DIS}	\overline{OE} to Q_N	Figure 1	2.7V	1	4.4	8.3	1	8.5	1	10.0	ns	
	0 = 10 Q _N		3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9.0		
tsk(0)	Output Skew Time		3.3V ± 0.3V			1.0				1.5	ns	

Operating Characteristics

 $T_A = +25^{\circ}C$

Symbol	Parameter	Test Conditions	V _{CC}	Тур	Unit
	Dower dissination	F = 10MHz	1.8V ± 0.15V	9.9	
$C_{\sf pd}$	Power dissipation capacitance per gate	Outputs Enabled -	$2.5V \pm 0.3V$	10.2	pF
	capacitance per gate		$3.3V \pm 0.3V$	10.6	

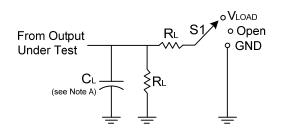
Package Characteristics

Symbol	Parameter	Package	Test Conditions	Min	Тур	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	TSSOP-20	(Note 9)	_	74	_	°C/W
θ _{JC}	Thermal Resistance Junction-to-Case	TSSOP-20	(Note 9)	_	15	_	°C/W
θ_{JA}	Thermal Resistance Junction-to-Ambient	V-QFN4525-20	(Note 9)	_	67	_	°C/W
θ _{JC}	Thermal Resistance Junction-to-Case	V-QFN4525-20	(Note 9)	_	20	_	°C/W

Note: 9. Test conditions for TSSOP-20 and V-QFN4525-20: Devices mounted on 4 layer FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout per JESD 51-7.

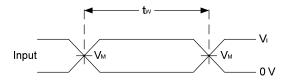


Parameter Measurement Information

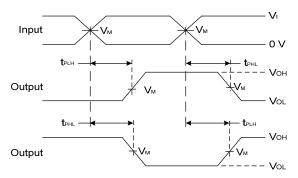


TEST	S 1
t _{PLH} /t _{PHL}	Open
t_{PLZ}/t_{PZL}	Vload
t _{PHZ} /t _{PZH}	GND

.,	In	puts	, , , , , , , , , , , , , , , , , , ,			_		
V _{cc}	Vı	t _r /t _f	V _M	V_{LOAD}	C∟	R∟	V Δ	
1.8V±0.15V	V _{CC}	≤2ns	V _{cc} /2	2 x V _{CC}	30pF	1ΚΩ	0.15V	
2.5V±0.2V	V_{CC}	≤2ns	V _{cc} /2	2 x V _{CC}	30pF	500Ω	0.15V	
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V	
3.3V±0.3V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V	



Voltage Waveform Pulse Duration



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Output ٧м ٧м Control 0 V Output VLOAD/2 Waveform 1 S1 at VLOAD Vol + V (see Note B) ← t_{PHZ} Output Waveform 2 Voh - Va S1 at GND (see Note B) ₩ 0V

Voltage Waveform Enable and Disable Times Low and High Level Enabling

A. Includes test lead and test apparatus capacitance. Notes:

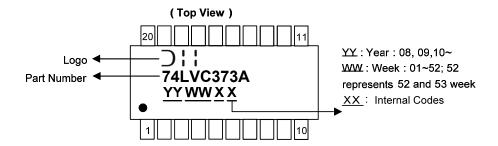
- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
- C. Inputs are measured separately one transition per measurement.
- D. t_{PLZ} and t_{PHZ} are the same as $t_{dis.}$
- E. t_{PZL} and t_{PZH} are the same as t_{EN0} F. t_{PLH} and t_{PHL} are the same as $t_{PD.}$

Figure 1 Load Circuit and Voltage Waveforms



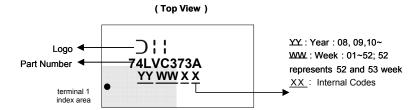
Marking Information

(1) TSSOP20



Part Number	Package
74LVC373AT20	TSSOP-20

(2) QFN-20 (V-QFN4525-20)



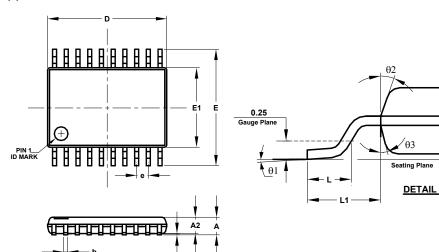
Part Number	Package
74LVC373AQ20	V-QFN4525-20



Package Outline Dimensions (All Dimensions in mm)

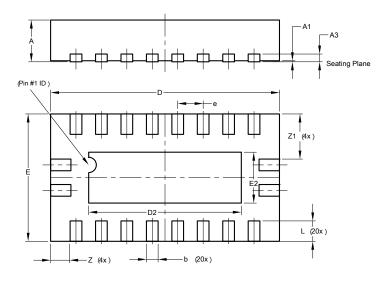
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

(1) TSSOP-20



TSSOP-20				
Dim	Min	Max	Тур	
Α	-	1.20	-	
A1	0.05	0.15	-	
A2	0.80	1.05	-	
b	0.19	0.30	-	
С	0.09	0.20	-	
D	6.40	6.60	6.50	
Е	6.20	6.60	6.40	
E1	4.30	4.50	4.40	
е	0.65 BSC			
L	0.45	0.75	0.60	
L1	1.0 REF			
θ1	0°	8°	-	
θ2	10°	14°	12°	
θ3	10°	14°	12°	
All Dimensions in mm				

(2) QFN-20 (V-QFN4525-20)



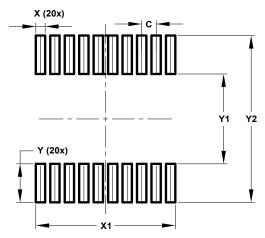
V-QFN4525-20				
Dim	Min	Max	Тур	
Α	0.75	0.85	0.80	
A1	0.00	0.05	0.02	
A3	-	-	0.15	
b	0.18	0.30	0.23	
D	4.45	4.55	4.50	
D2	2.85	3.15	3.00	
Е	2.45	2.55	2.50	
E2	0.85	1.15	1.00	
е	0.50BSC			
L	0.30	0.50	0.40	
Z	-	-	0.385	
Z1	-	-	0.885	
All Dimensions in mm				



Suggested Pad Layout

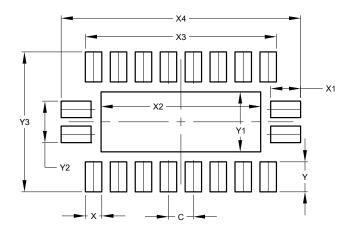
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

(1) TSSOP-20



Dimensions	Value (in mm)
С	0.650
Х	0.420
X1	6.270
Υ	1.789
Y1	4.160
Y2	7.720

(2) QFN-20 (V-QFN4525-20)



Dimensions	Value (in mm)
С	0.500
X	0.330
X1	0.600
X2	3.200
Х3	3.830
X4	4.800
Υ	0.600
Y1	1.200
Y2	0.830
V3	2 800



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2014, Diodes Incorporated

www.diodes.com